

BAP64Q

Quad PIN diode attenuator

Rev. 1 — 7 October 2010

Product data sheet

1. Product profile

1.1 General description

Quad PIN diode in a SOT753 package.

1.2 Features and benefits

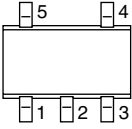
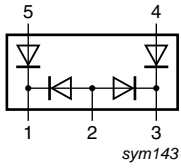
- 4 PIN diodes in a SOT753 package
- 300 kHz to 4 GHz
- High linearity
- Low insertion loss
- reduction in part count
- Low diode capacitance
- Low diode forward resistance

1.3 Applications

- RF attenuators
- Broadband system applications
- General purpose Voltage Controlled Attenuators for high linearity applications

2. Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	RF in		 <i>sym143</i>
2	series bias		
3	RF out		
4	shunt 1 bias		
5	shunt 2 bias		

3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP64Q	SC-74A	plastic surface-mounted package; 5 leads	SOT753



4. Marking

Table 3. Marking

Type number	Marking code
BAP64Q	A1

5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		[1]	100	V
I_F	forward current		[1]	100	mA
P_{tot}	total power dissipation	$T_{sp} = 90\text{ °C}$	[1]	125	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

[1] single diode.

6. Thermal characteristics

Table 5. Thermal characteristics

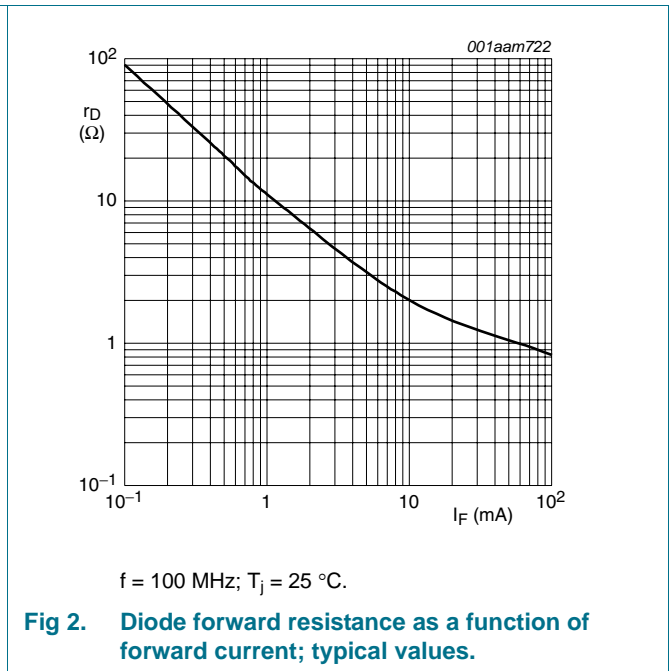
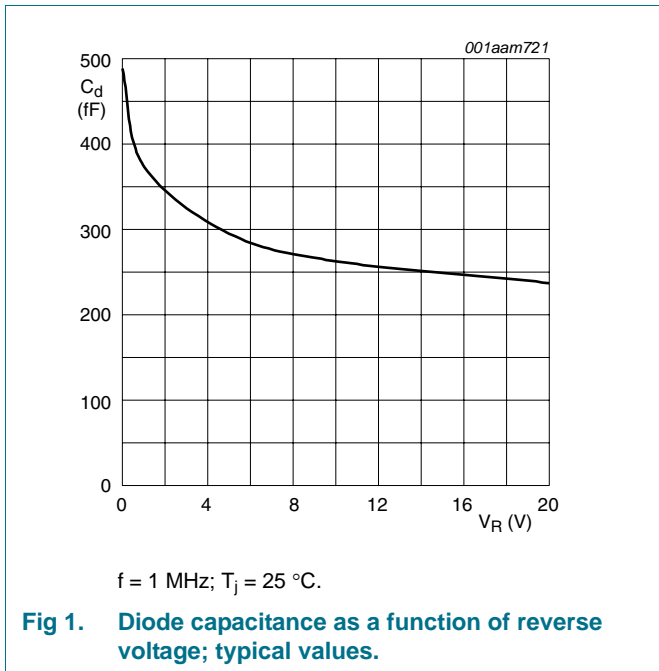
Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		350	K/W

7. Characteristics

Table 6. Characteristics
T_j = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Per diode							
V _F	forward voltage	I _F = 50 mA	-	0.95	1.1	V	
I _R	reverse current	V _R = 20 V	-	-	1	μA	
		V _R = 100 V	-	-	10	μA	
C _d	diode capacitance	f = 1 MHz; see Figure 1					
		V _R = 0 V	-	0.52	-	pF	
		V _R = 1 V	-	0.37	-	pF	
		V _R = 20 V	-	0.23	0.35	pF	
r _D	diode forward resistance	f = 100 MHz; see Figure 2					
		I _F = 0.5 mA	[1]	-	20	40	Ω
		I _F = 1 mA	[1]	-	10	20	Ω
		I _F = 10 mA	[1]	-	2	3.8	Ω
		I _F = 100 mA	[1]	-	0.7	1.35	Ω
τ _L	charge carrier life time	when switched from I _F = 10 mA to I _R = 6 mA; R _L = 100 Ω; measured at I _R = 3 mA	-	1.55	-	μs	

[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.



8. Application information

8.1 Application circuit

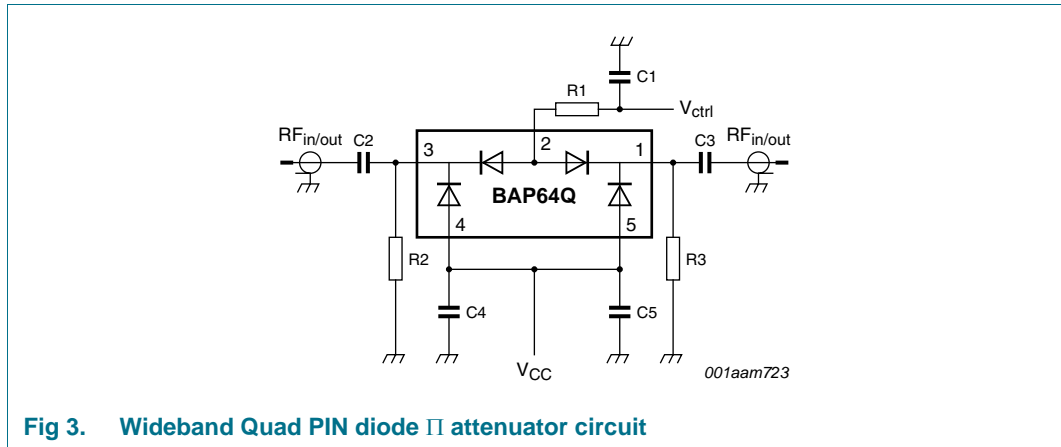


Fig 3. Wideband Quad PIN diode Π attenuator circuit

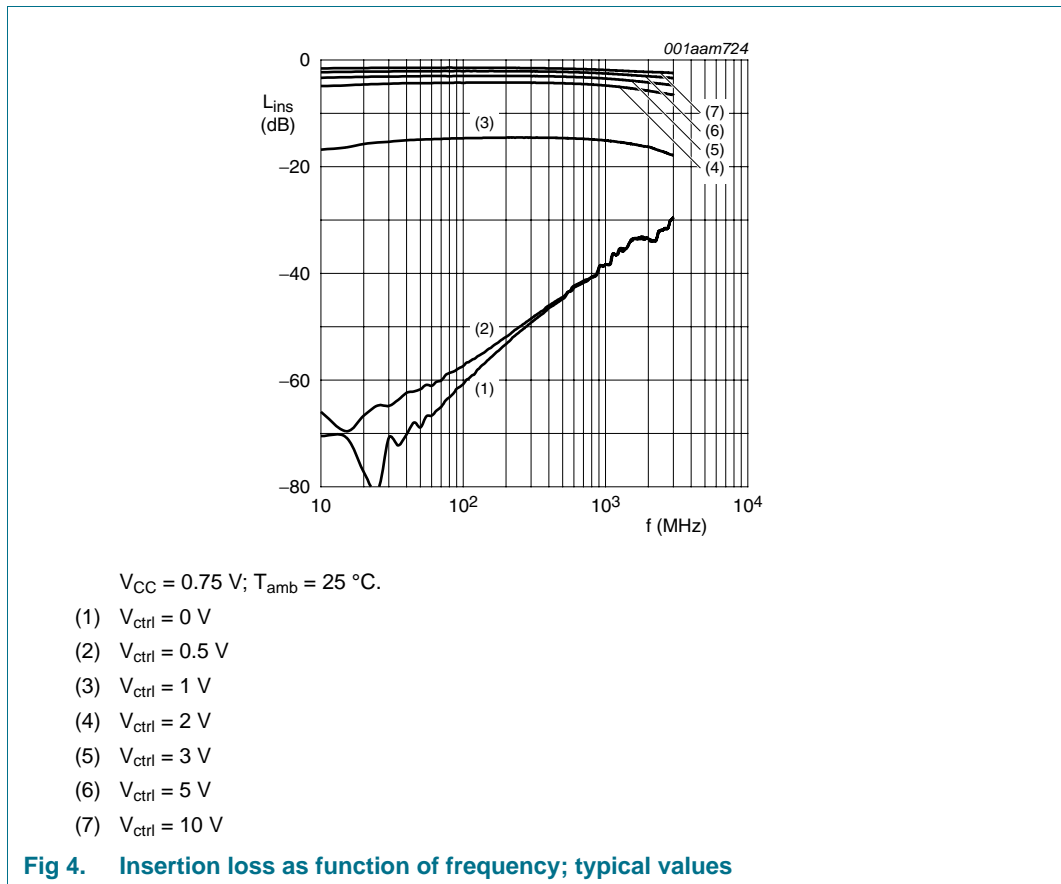
Table 7. List of components used for the typical application

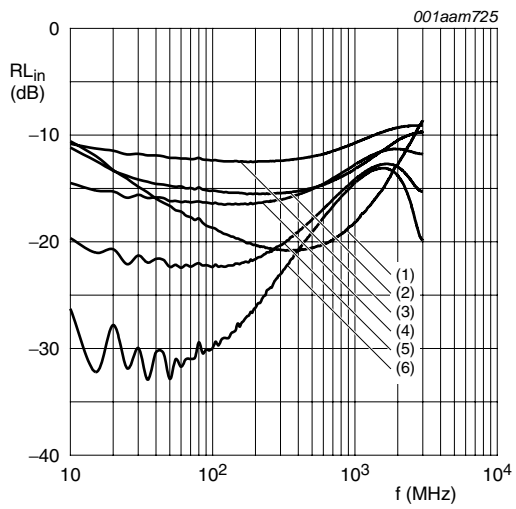
Component	Description	Value
C1, C2, C3, C4, C5	chip capacitor	10 nF
R1, R2, R3	chip resistor	1000 Ω

8.2 Quad PIN pi attenuator characteristics

Table 8. Typical performance for BAP64Q quad PIN diode π attenuator
 $V_{CC} = 0.75\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Test Conditions	Typ	Units
L_{ins}	insertion loss	$V_{ctrl} = 10\text{ V}$; $f = 1\text{ GHz}$	1.8	dB
RL_{in}	input return loss	$V_{ctrl} = 0\text{ V}$; $f = 1\text{ GHz}$	18	dB
α	attenuation	$V_{ctrl} = 0\text{ V}$; $f = 1\text{ GHz}$	38	dB
$IP3_i$	input third-order intercept point	$f = 0.1\text{ GHz}$		
		$V_{ctrl} = 2\text{ V}$	32	dBm
		$V_{ctrl} = 10\text{ V}$	42	dBm
		$f = 0.9\text{ GHz}$		
		$V_{ctrl} = 2\text{ V}$	40	dBm
		$V_{ctrl} = 10\text{ V}$	41	dBm
		$f = 1.8\text{ GHz}$		
		$V_{ctrl} = 2\text{ V}$	40	dBm
		$V_{ctrl} = 10\text{ V}$	37	dBm
		$f = 2.1\text{ GHz}$		
		$V_{ctrl} = 2\text{ V}$	38	dBm
		$V_{ctrl} = 10\text{ V}$	39	dBm

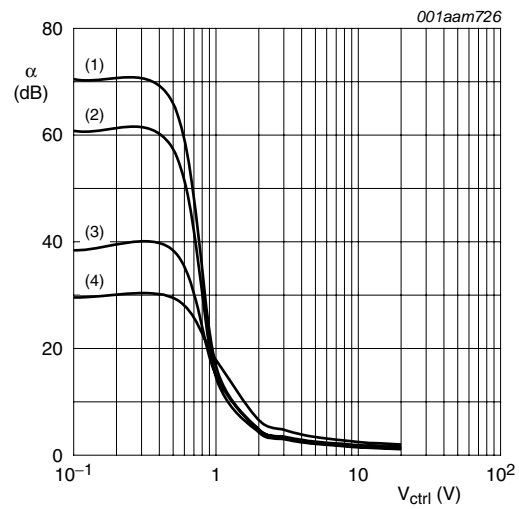




$V_{CC} = 0.75 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}.$

- (1) $V_{ctrl} = 0 \text{ V}$
- (2) $V_{ctrl} = 1 \text{ V}$
- (3) $V_{ctrl} = 2 \text{ V}$
- (4) $V_{ctrl} = 3 \text{ V}$
- (5) $V_{ctrl} = 5 \text{ V}$
- (6) $V_{ctrl} = 10 \text{ V}$

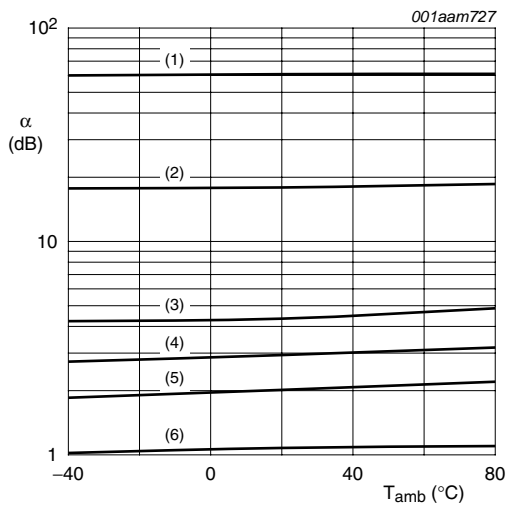
Fig 5. Return loss as function of frequency; typical values



$V_{CC} = 0.75 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}.$

- (1) $f = 10 \text{ MHz}$
- (2) $f = 100 \text{ MHz}$
- (3) $f = 1000 \text{ MHz}$
- (4) $f = 3000 \text{ MHz}$

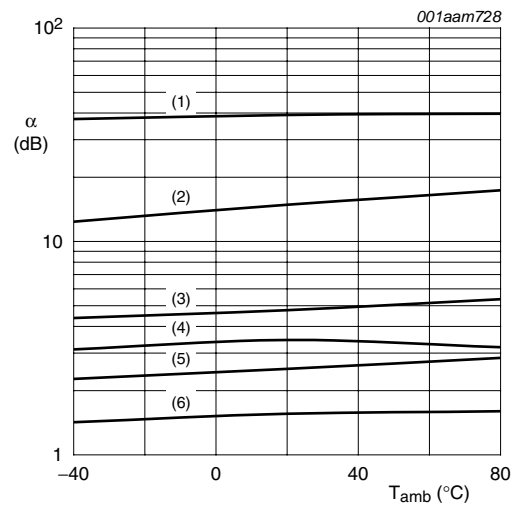
Fig 6. Attenuation as function of control voltage; typical values



$V_{CC} = 0.75 \text{ V}; f = 100 \text{ MHz.}$

- (1) $V_{ctrl} = 0 \text{ V}$
- (2) $V_{ctrl} = 1 \text{ V}$
- (3) $V_{ctrl} = 2 \text{ V}$
- (4) $V_{ctrl} = 3 \text{ V}$
- (5) $V_{ctrl} = 5 \text{ V}$
- (6) $V_{ctrl} = 10 \text{ V}$

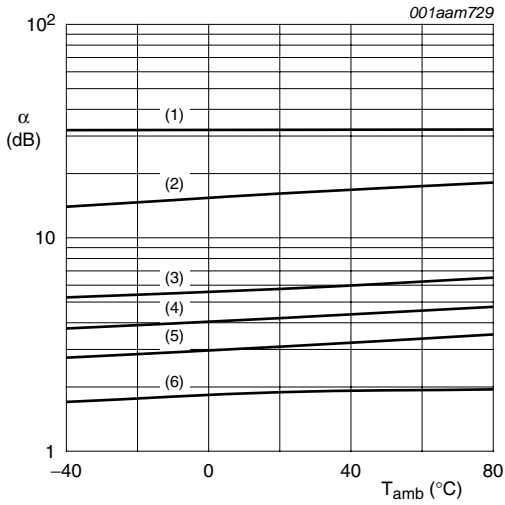
Fig 7. Attenuation as function of temperature; typical values



$V_{CC} = 0.75 \text{ V}; f = 1000 \text{ MHz.}$

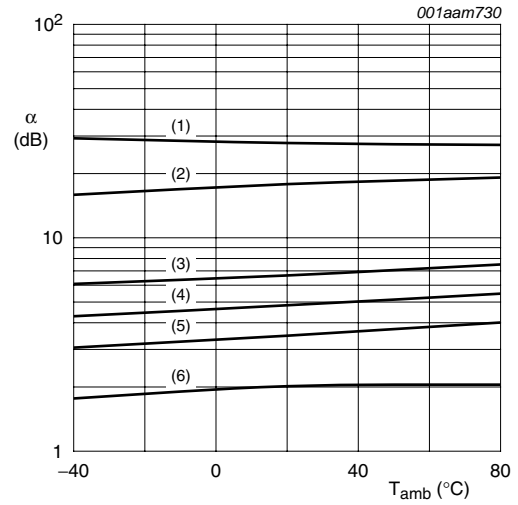
- (1) $V_{ctrl} = 0 \text{ V}$
- (2) $V_{ctrl} = 1 \text{ V}$
- (3) $V_{ctrl} = 2 \text{ V}$
- (4) $V_{ctrl} = 3 \text{ V}$
- (5) $V_{ctrl} = 5 \text{ V}$
- (6) $V_{ctrl} = 10 \text{ V}$

Fig 8. Attenuation as function of temperature; typical values



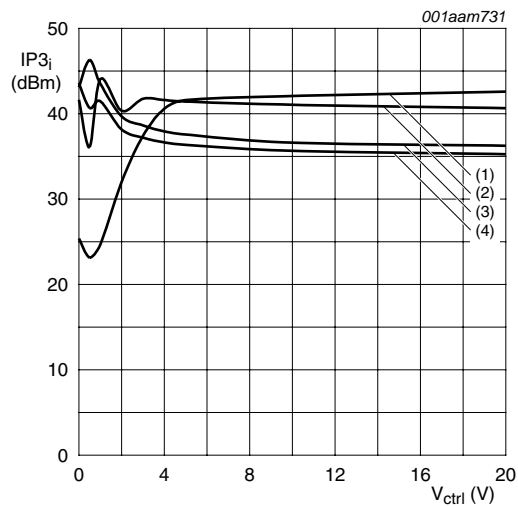
$V_{CC} = 0.75 \text{ V}; f = 2000 \text{ MHz}.$
 (1) $V_{ctrl} = 0 \text{ V}$
 (2) $V_{ctrl} = 1 \text{ V}$
 (3) $V_{ctrl} = 2 \text{ V}$
 (4) $V_{ctrl} = 3 \text{ V}$
 (5) $V_{ctrl} = 5 \text{ V}$
 (6) $V_{ctrl} = 10 \text{ V}$

Fig 9. Attenuation as function of temperature; typical values



$V_{CC} = 0.75 \text{ V}; f = 3000 \text{ MHz}.$
 (1) $V_{ctrl} = 0 \text{ V}$
 (2) $V_{ctrl} = 1 \text{ V}$
 (3) $V_{ctrl} = 2 \text{ V}$
 (4) $V_{ctrl} = 3 \text{ V}$
 (5) $V_{ctrl} = 5 \text{ V}$
 (6) $V_{ctrl} = 10 \text{ V}$

Fig 10. Attenuation as function of temperature; typical values



$V_{CC} = 0.75 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}.$
 (1) $f = 100 \text{ MHz}$
 (2) $f = 900 \text{ MHz}$
 (3) $f = 1800 \text{ MHz}$
 (4) $f = 2100 \text{ MHz}$

Fig 11. Input third-order intercept point as control voltage; typical values

9. Package outline

Plastic surface-mounted package; 5 leads

SOT753

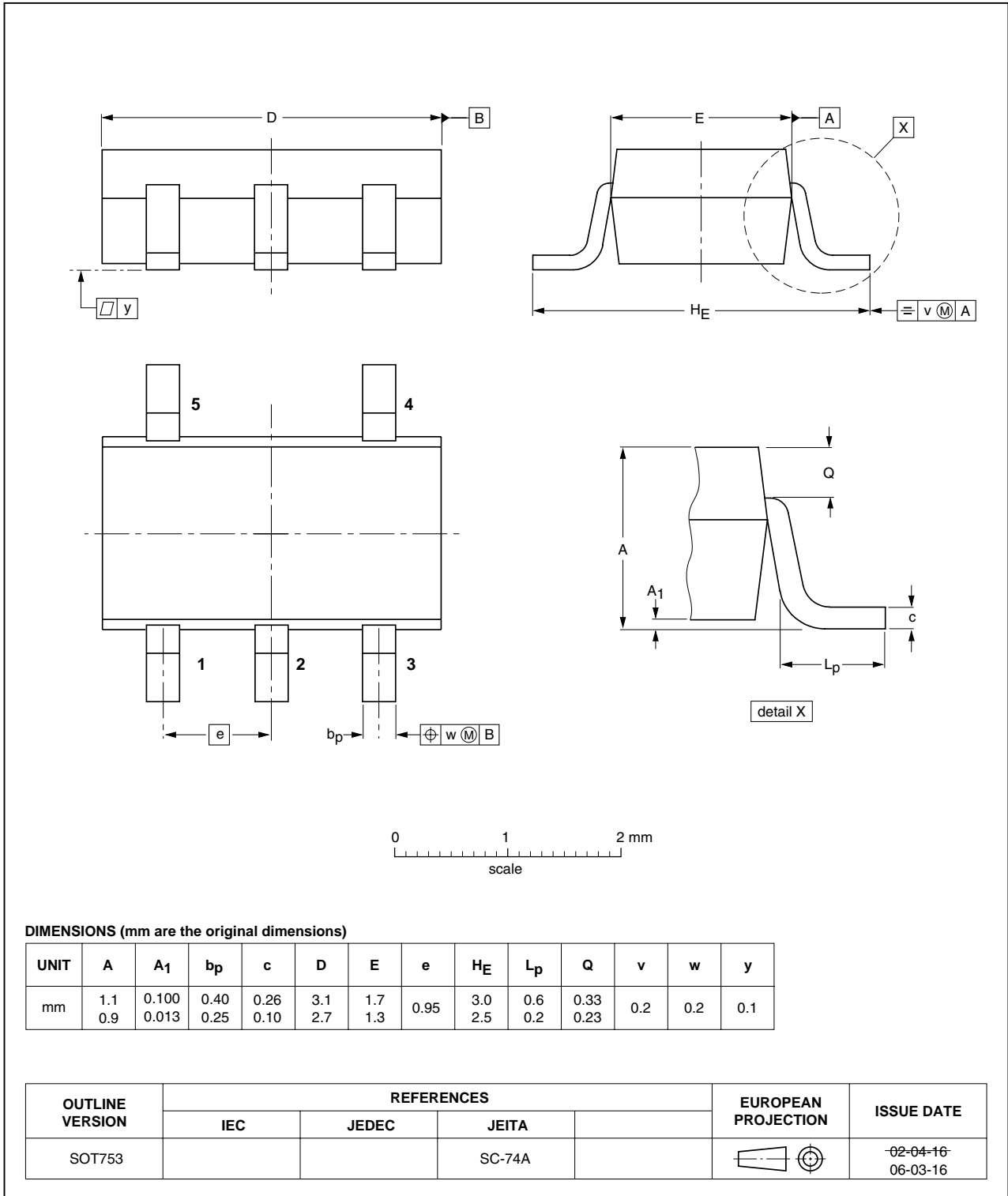


Fig 12. Package outline SOT753

10. Abbreviations

Table 9. Abbreviations

Acronym	Description
AQL	Acceptable Quality Level
PIN	P-type, Intrinsic, N-type
RF	Radio Frequency
S4	Special inspection level 4

11. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP64Q v.1	20101007	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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14. Contents

1	Product profile	1
1.1	General description	1
1.2	Features and benefits	1
1.3	Applications	1
2	Pinning information	1
3	Ordering information	1
4	Marking	2
5	Limiting values	2
6	Thermal characteristics	2
7	Characteristics	3
8	Application information	4
8.1	Application circuit	4
8.2	Quad PIN pi attenuator characteristics	5
9	Package outline	9
10	Abbreviations	10
11	Revision history	10
12	Legal information	11
12.1	Data sheet status	11
12.2	Definitions	11
12.3	Disclaimers	11
12.4	Trademarks	12
13	Contact information	12
14	Contents	13

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